Report No. MCR-23-0444-B
October 01,2026

RELIABILITY REPORT

GROUP : RA8M1

DEVICE : R7FA8M1XXX

QUALITY GRADE : Standard

Quality Assurance Div.
Renesas Electronics Corporation

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Summary of Reliability Test Results for QFP Package (MSL3)

Test Item	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Tj=125 ℃, Vccmax, 1000 hrs	0/231	3 lots or more
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (HAST) (*1)	JESD22-A110	Ta=110 ℃, RH=85 %, Vccmax, 264 hrs	0/75	3 lots or more
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 500 cycles	0/75	3 lots or more
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500 V,1 time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (MSL3)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3) Peak Reflow Temp=260 °C	Pass	Verified after MSL preconditioning; applied to applicable reliability tests (*1).

Note :
- (*1) With preconditioning per JESD22-A113, MSL 3
- It is tested to confirm that all the samples are satisfied with an individual product specification.
- Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

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Summary of Reliability Test Results for BGA Package (MSL3)

Test Item	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Tj=125 ℃, Vccmax, 1000 hrs	0/231	3 lots or more
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/25	
Temperature Humidity bias (HAST) (*1)	JESD22-A110	Ta=110 ℃, RH=85 %, Vccmax, 264 hrs	0/75	3 lots or more
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 ℃ to 125 ℃ , 700 cycles	0/75	3 lots or more
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500 V,1 time	0/3	Class: C2
Resistance to Soldering Heat (MSL3)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3) Peak Reflow Temp=260 °C	Pass	Verified after MSL preconditioning; applied to applicable reliability tests (*1).

Note :
- (*1) With preconditioning per JESD22-A113, MSL 3
- It is tested to confirm that all the samples are satisfied with an individual product specification.
- Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

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The failure rate of the device in an actual use condition can be estimated by the below procedure.

・Equation for the failure rate estimation (λ)

$$\lambda = \lambda b \times \pi T \ (FIT)$$

①Unique failure rate (λb)

λb= 0.007 FIT

Unique failure rate at Ta=55 ℃ using 60 % confidence level.

②Temperature term (πT)

$$\pi T = exp\{11600 \times Ea \times (1/(273+55) - 1/(273+Ta))\}$$

Ea： Activation energy（eV)
Ta： Ambient temperature（℃)

πT simplified chart as Ea=0.7 eV												
Ta (℃)	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

・MTTF (Mean Time To Failure)

$$MTTF = 1/\lambda$$

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Reference about Renesas package code

Package type		Package code *1
Lead type plastic package	QFP	PxQP
	SOP	PxSP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG
Wafer level chip scale package	WLCSP	SxBG

*1. First four digit

Table. Product list

No	Product part number	Package code	MSL	No	Product part number	Package code	MSL
1	R7FA8M1AFECBD	PLBG0224G*	MSL3	51			
2	R7FA8M1AHECBD	PLBG0224G*	MSL3	52			
3	R7FA8M1AFECFB	PLQP0144K*	MSL3	53			
4	R7FA8M1AHECFB	PLQP0144K*	MSL3	54			
5	R7FA8M1AFECFC	PLQP0176K*	MSL3	55			
6	R7FA8M1AHECFC	PLQP0176K*	MSL3	56			
7	R7FA8M1AFECFP	PLQP0100K*	MSL3	57			
8	R7FA8M1AHECFP	PLQP0100K*	MSL3	58			
9				59			
10				60			
11				61			
12				62			
13				63			
14				64			
15				65			
16				66			
17				67			
18				68			
19				69			
20				70			
21				71			
22				72			
23				73			
24				74			
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26				76			
27				77			
28				78			
29				79			
30				80			
31				81			
32				82			
33				83			
34				84			
35				85			
36				86			
37				87			
38				88			
39				89			
40				90			
41				91			
42				92			
43				93			
44				94			
45				95			
46				96			
47				97			
48				98			
49				99			
50				100			

Note: MSL stands for Moisture Sensitivity Level.

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